AMENDMENTS TO THE CLAIMS

Please amend claims 1, 4, 5 and 9. Please add new claim 10. No new matter is believed to be introduced as a result of the aforementioned amendments. The following listing of claims replaces all prior versions and listings of claims in this application.

1. **(Currently amended)** A method of manufacturing an optical transceiver module ~~using a lead frame connector~~, comprising:

connecting a plurality of electrical contacts of a lead frame connector to corresponding leads of ~~the~~ an optical sub-assembly to obtain a combined structure that includes the lead frame connector and the optical sub-assembly; and

~~connecting a plurality of leads of the lead frame connector to corresponding conductive structures on a printed circuit board of the optical transceiver module~~

rigidly attaching the optical assembly to a printed circuit board using the lead frame connector such that the lead frame connector electrically connects the optical sub-assembly to the printed circuit board and the lead frame connector provides mechanical support for the optical transceiver module.

2. **(Original)** The method as defined in claim 1, wherein connecting the plurality of electrical contacts comprises:

passing each of the leads of the optical sub-assembly through a hole in the corresponding electrical contact; and

soldering the leads to the corresponding electrical contacts.

3. **(Original)** The method as defined in claim 2, wherein soldering the leads to the corresponding electrical contacts is performed by applying the solder to the electrical contacts at a side of the lead frame connector that is opposite a side that is adjacent to the optical sub-assembly.

4. **(Currently amended)** The method as defined in claim ~~1~~ 10, wherein connecting the plurality of leads of the lead frame connector to the corresponding conductive structures on a printed circuit board comprises:

placing the leads of the lead frame connector in contact with the corresponding conductive structures; and

reflow soldering the leads to the conductive structures.

5. **(Currently amended)** The method as defined in claim ~~1~~ 10, wherein connecting the plurality of leads of the lead frame connector to the corresponding conductive structures on a printed circuit board comprises:

placing the leads of the lead frame connector in contact with the corresponding conductive structures; and

connecting the leads to the conductive structures using a hot bar process.

6. **(Original)** The method as defined in claim 1, wherein the optical sub-assembly is a transmitter optical sub-assembly.

7. **(Original)** The method as defined in claim 1, wherein the optical sub-assembly is a receiver optical sub-assembly.

8. **(Original)** The method as defined in claim 1, wherein connecting the plurality of electrical contacts to corresponding leads includes self-alignment of the lead frame connector with respect to the optical sub-assembly as the corresponding leads pass through holes in the electrical contacts.

9. **(Currently amended)** A method of manufacturing an optical transceiver module ~~using a lead frame connector~~, comprising:

obtaining a lead frame connector that includes:

an electrically insulating casing; and

a plurality of conductors that are electrically isolated one from another by the electrically insulating casing, the plurality of conductors forming:

a plurality of electrical contacts that correspond to leads of the optical sub-assembly; and

a plurality of leads that correspond to conductive structures on the printed circuit board;

connecting the plurality of electrical contacts of the lead frame connector to the corresponding leads of ~~the~~ an optical sub-assembly to obtain a combined structure that includes the lead frame connector and the optical sub-assembly; and

~~connecting the plurality of leads of the lead frame connector to the corresponding conductive structures on a printed circuit board of the optical transceiver module~~

rigidly attaching the optical assembly to a printed circuit board using the lead frame connector such that the lead frame connector electrically connects the optical sub-assembly to the printed circuit board and the lead frame connector provides mechanical support for the optical transceiver module.

10. **(New)** The method as defined in claim 1, wherein rigidly attaching the optical assembly to the printed circuit board using the lead frame connector comprises connecting a plurality of leads of the lead frame connector to corresponding conductive structures on the printed circuit board of the optical transceiver module.